



#9/Amend
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JH

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John J. Kelly, Jr.

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Examiner: Alonzo Chambliss
Art Unit: 2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: K. TATSUMI et al.
Serial No.: 09/632,910
Filed : August 4, 2000
For : SEMICONDUCTOR DEVICE PROVIDED WITH LOW MELTING POINT METAL BUMPS AND PROCESS FOR PRODUCING SAME

Commissioner for Patents
Washington, D.C. 20231

AMENDMENT UNDER RULE 116

SIR:

Kindly amend the claims of the above-identified patent application as follows.

In The Title

Cancel the current title of the invention and replace it with the following new title.

--METHOD FOR FABRICATING A SEMICONDUCTOR DEVICE PROVIDED WITH LOW MELTING POINT METAL BUMPS--.

In The Claims

--16. (Amended) A process for producing a semiconductor device to be mounted on a substrate by flip chip bonding comprising: electrodes formed on a semiconductor chip, and bumps each consisting of a spherically formed metal ball having a given size, and adhesive bonded to the electrodes (8) for the attachment of the bumps, wherein each electrode (8) includes a layer of an

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